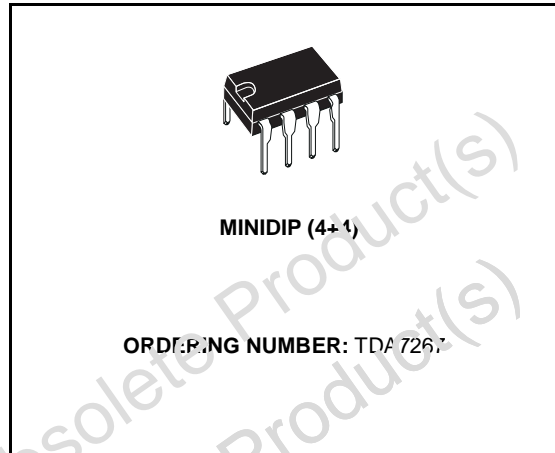


2W MONO AMPLIFIER

- CAN DELIVER 2W THD 10% 12V/8Ω
- INTERNAL FIXED GAIN 32dB
- NO FEEDBACK CAPACITOR
- NO BOUCHEROT CELL
- THERMAL PROTECTION
- AC SHORT CIRCUIT PROTECTION
- SVR CAPACITOR FOR BETTER RIPPLE REJECTION
- LOW TURN-ON/OFF POP
- STAND-BY MODE



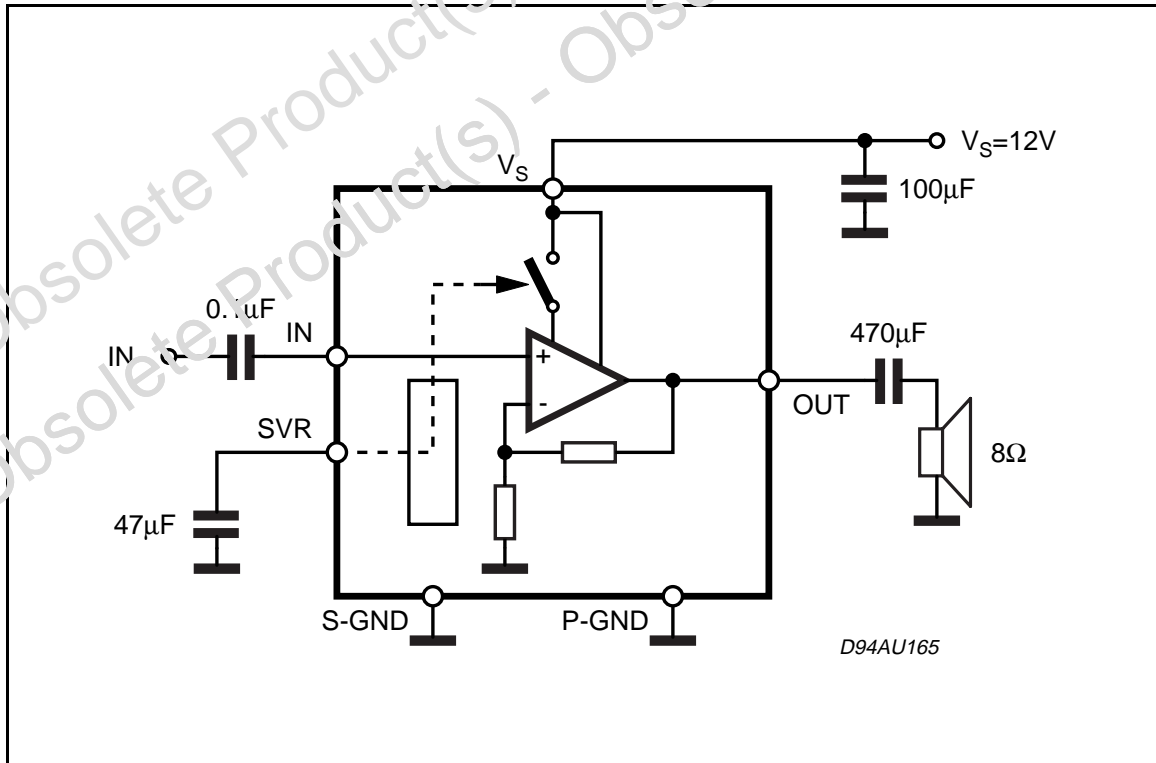
DESCRIPTION

The device TDA7267 is a new technology Mono Audio Amplifier in MINIDIP package specifically designed for TV application.

Thanks to the fully complementary output configura-

tion the device delivers a rail to rail voltage swing without need of bootstrap capacitors.

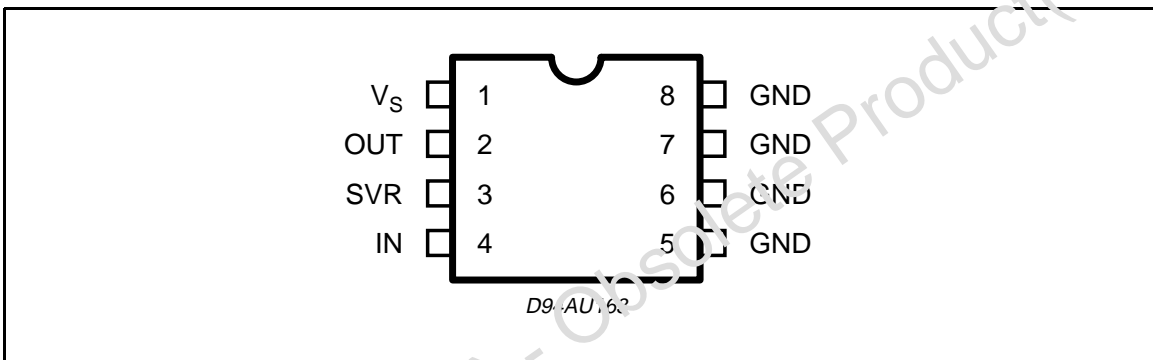
BLOCK DIAGRAM



ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V _S	Operating Supply Voltage	18	V
I _O	Output Put Peak Current	1.5	A
T _{op}	Operating Temperature Range	0 to 70	°C
T _j	Junction Temperature	150	°C
T _{stg}	Storage Temperature Range	-40 to 125	°C

PIN CONNECTION (Top view)



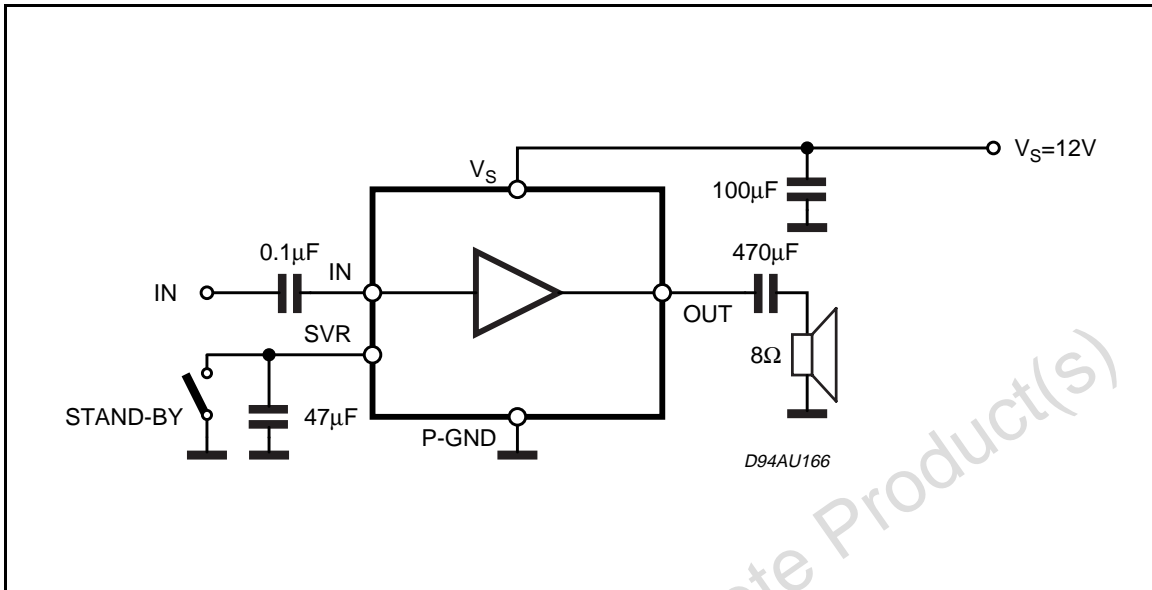
THERMAL DATA

Symbol	Parameter	Value	Unit
R _{th j-amb}	Thermal Resistance Junction to ambient (on PCB)	80	°C/W
R _{th j-case}	Thermal Resistance Junction to case	15	°C/W

ELECTRICAL CHARACTERISTICS (T_{amb} = 25°C; V_S = 12V; R_L = 8Ω; f = 1KHz; unless otherwise specified.)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
V _S	Supply Voltage Range		4.5		18	V
I _S	Quiescent Current			20	30	mA
I _{sb}	Stand-By Current	Pin 3 shorted to GND			0.3	mA
V _O	Quiescent Output Voltage			6		V
A _V	Voltage Gain			32		dB
R _{IN}	Input Impedance			100		KΩ
P _O	Output Power	THD = 10%	1.8	2		W
THD	Distortion	P _O = 1W			1.0	%
SVR	Supply Voltage Rejection	V _{ripple} = 150mVrms; F _{ripple} = 1KHz		50		dB
E _I	Input Noise Voltage	R _g = 10KΩ; BW = 20Hz to 20KHz		1.5	5	μV
V _{sb}	Stand-By Enable Voltage				1	V

APPLICATION CIRCUIT

**APPLICATION HINTS:**

For 12V supply and 8Ω speaker application, its maximum power dissipation is about 1W.

Assuming that max ambient temperature is 70°C. Required thermal resistance of the device and heat dissipating means must be equal to $(150 - 70)/1 = 80^\circ\text{C}/\text{W}$.

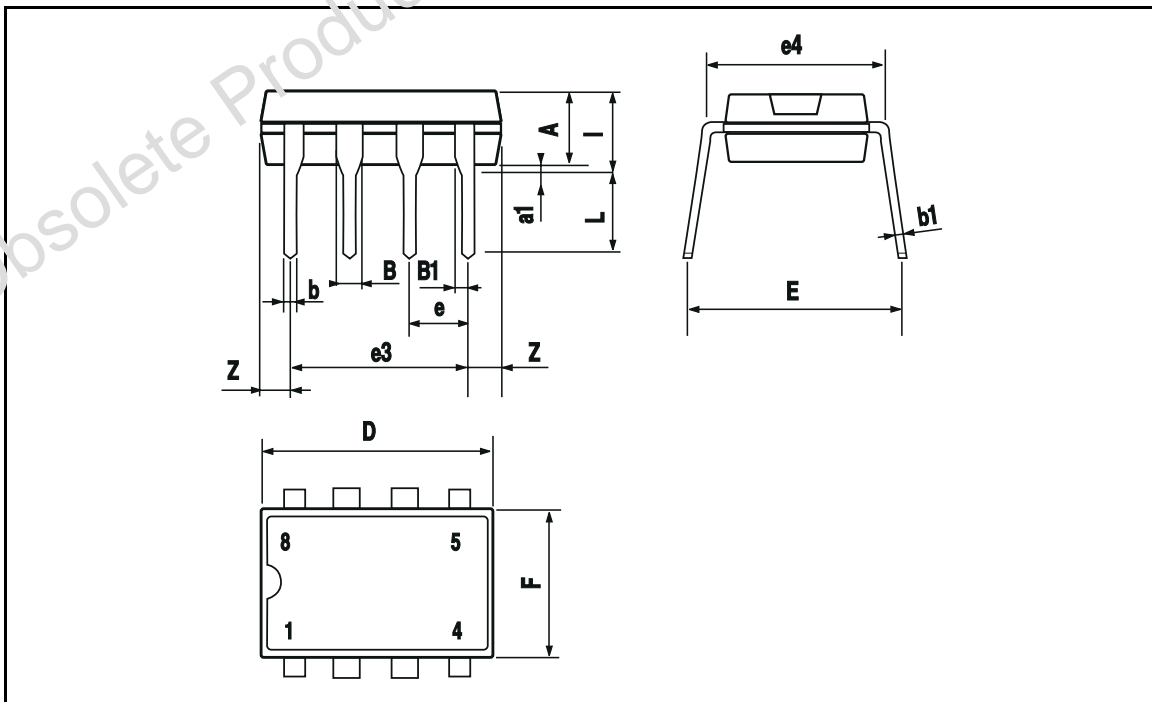
Junction to pin thermal resistance of the package is about 15°C/W. That means external heat sink of about 65°C/W is required.

Cu ground plane of PCB can be used as heat dissipating means.

Stand-By switches must be able to discharge C_{SVR} current.

MINIDIP PACKAGE MECHANICAL DATA

DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A		3.3			0.130	
a1	0.7			0.028		
B	1.39		1.65	0.055		0.065
B1	0.91		1.04	0.036		0.041
b		0.5			0.020	
b1	0.38		0.5	0.015		0.020
D			9.8			0.386
E		8.8			0.346	
e		2.54			0.100	
e3		7.62			0.300	
e4		7.62			0.300	
F			7.1			0.280
I			1.3			0.189
L		3.3			0.130	
Z	0.44		1.6	0.017		0.063



Obsolete Product(s) - Obsolete Product(s)

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